PCN Number:	20190328001.0 PC		PCN Date:	March 29, 2019			19	
Title: Datasheet for TAS2557								
Customer Contact:	PCN Manager			D)ep	ot:	Quality Services	
Change Type:								
Assembly Site		Design				Wafer I	Bump Site	
Assembly Process		Data Sheet				Wafer Bump Material		
Assembly Materials		Part number change			╡	Wafer Bump Process		
Mechanical Specification		Test Site			╡╎	Wafer Fab Site Wafer Fab Materials		
Packing/Shipping/I	Test Process			╡╢	Wafer Fab Process			
Notification Details						-dD PIOCESS		
Description of Change:								
Texas Instruments Incorporated is announcing an information only notification.								
The product datasheet(enreación		
The following change h								
TEXAS INSTRUMENTS							TAS2557	
INSTRUMENTS			SLAS	EC2B -	-NO	VEMBER 20	16-REVISED FEBRUARY 2019	
Changes from Revision A (F	ebruary 2017) to	Revision B					Page	
Added Boost, Switching, F	Regulator voltage a	and Note 2 to th	e Absolute Maxim	num R	Rati	ngs table .	6	
	-					-		
The datasheet number v	vill be changin	g.						
Device Family			Change I	Change From:			Change To:	
· · ·				SLASEC2A			SLASEC2B	
TAS2557 These changes may be								
2 ,			iniks provided	4.				
http://www.ti.com/proc	auct/TAS2557							
Reason for Change:								
To accurately reflect de	evice character	istics.						
Anticipated impact o	n Fit, Form, F	unction, Q	uality or Reli	abili	ity	(positi	ive / negative):	
No anticipated impact.	This is a specit	fication char	ige announcen	nent	or	nly. Ther	re are no changes to	
the actual device.								
Changes to product i	dentification	resulting f	rom this PCN	:				
None.								
Product Affected:								
TAS2557YZR	TAS2557Y	ZT						
			1					

or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com